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DATE: 9th July, 2014

PCN #: 2136

PCN Title: Qualification of "Yangzhou YangJie Electronic Technology Company Limited" as an Additional Assembly & Test Site and "J & V Semiconductor" as an Additional Wafer Source for Selected Discrete Devices, and Qualification of New Lead Frame and Clip for Selected GBJ Devices

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



**PRODUCT CHANGE NOTICE**

**PCN-2136 REV 00**

<b>Notification Date:</b>	<b>Implementation Date:</b>	<b>Product Family:</b>	<b>Change Type:</b>	<b>PCN #:</b>
9th July, 2014	8th October, 2014	Discrete Products	Additional Assembly & Test Site / New Wafer Source / Lead Frame and Clip structure	<b>2136</b>
<b>TITLE</b>				
Qualification of "Yangzhou YangJie Electronic Technology Company Limited" as an Additional Assembly & Test Site and "J & V Semiconductor" as an Additional Wafer Source for Selected Discrete Devices, and Qualification of New Lead Frame and Clip for Selected GBJ Devices				
<b>DESCRIPTION OF CHANGE</b>				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified Yangzhou YangJie Electronic Technology Company Limited" as an Additional Assembly &amp; Test Site and "J &amp; V Semiconductor" as an Additional Wafer Source for selected discrete devices.</p> <p>Additionally, in order to improve GBJ package body strength and gain better device power dissipation capability, Diodes Incorporated has qualified a new lead frame structure and clip layout for selected GBJ products.</p> <p>Full electrical characterization and high reliability testing have been completed to ensure that no changes in product reliability, device functionality or data sheet electrical specifications exist.</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p>				
<b>IMPACT</b>				
No change in datasheet parameters and product performance				
<b>PRODUCTS AFFECTED</b>				
Please refer to Table 1 for Additional A/T Site and Wafer Source Please refer to Table 2 for Additional A/T Site and Wafer Source, and Change of Lead Frame / Clip Layout at the current A/T site Please refer to Table 3 for Change of Lead Frame / Clip Layout at the current A/T Site				
<b>WEB LINKS</b>				
<b>Manufacturer's Notice:</b>	<a href="http://www.diodes.com/quality/pcns">http://www.diodes.com/quality/pcns</a>			
<b>For More Information Contact:</b>	<a href="http://www.diodes.com/contacts">http://www.diodes.com/contacts</a>			
<b>Data Sheet:</b>	<a href="http://www.diodes.com/products">http://www.diodes.com/products</a>			
<b>DISCLAIMER</b>				
<b>Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.</b>				

<b>Table 1 - Additional A/T Site and Wafer Source</b>				
RS2M-13-F	S2JA-13-F	RS1K-13-F	GBU810	GBU402
RS2MA-13-F	S2J-13-F	RS1J-13-F	GBU808	GBU401
RS2KA-13-F	S2GA-13-F	RS1G-13-F	GBU806	GBU1010
RS2K-13-F	S2G-13-F	RS1D-13-F	GBU804	GBU1008
RS2JA-13-F	S2DA-13-F	RS1B-13-F	GBU802	GBU1006
RS2J-13-F	S2D-13-F	RS1A-13-F	GBU801	GBU1004
RS2GA-13-F	S2BA-13-F	ES2D-13-F	GBU8005	GBU1002
RS2G-13-F	S2B-13-F	ES2DA-13-F	GBU610	GBU1001
RS2DA-13-F	S2AA-13-F	ES2CA-13-F	GBU608	GBU10005
RS2D-13-F	S2A-13-F	ES2C-13-F	GBU606	1N4007G-T
RS2BA-13-F	S1M-13-F	ES2BA-13-F	GBU604	1N4006G-T
RS2B-13-F	S1K-13-F	ES2B-13-F	GBU602	1N4005G-T
RS2AA-13-F	S1J-13-F	ES2AA-13-F	GBU601	1N4004G-T
RS2A-13-F	S1G-13-F	ES2A-13-F	GBU6005	1N4003G-T
S2M-13-F	S1D-13-F	HD06-T	GBU410	1N4002G-T
S2MA-13-F	S1B-13-F	HD04-T	GBU408	1N4001G-T
S2KA-13-F	S1A-13-F	HD02-T	GBU406	
S2K-13-F	RS1M-13-F	HD01-T	GBU404	

<b>Table 2 - Additional A/T Site and Wafer Source, and Change of Lead Frame / Clip Layout at the current A/T Site</b>				
GBJ2510-F	GBJ2501-F	GBJ1504-F	GBJ1008-F	GBJ10005-F
GBJ2508-F	GBJ25005-F	GBJ1502-F	GBJ1006-F	
GBJ2506-F	GBJ1510-F	GBJ1501-F	GBJ1004-F	
GBJ2504-F	GBJ1508-F	GBJ15005-F	GBJ1002-F	
GBJ2502-F	GBJ1506-F	GBJ1010-F	GBJ1001-F	

<b>Table 3 – Change of Lead Frame / Clip Layout at the current A/T Site</b>				
GBJ810-F	GBJ801-F	GBJ604-F	GBJ2008-F	GBJ20005-F
GBJ808-F	GBJ8005-F	GBJ602-F	GBJ2006-F	
GBJ806-F	GBJ610-F	GBJ601-F	GBJ2004-F	
GBJ804-F	GBJ608-F	GBJ6005-F	GBJ2002-F	
GBJ802-F	GBJ606-F	GBJ2010-F	GBJ2001-F	